

LV10T150B

Rev.E May.-2016

/ Descriptions

TO-263

Schottky Diode in a TO-263 Plastic Package.

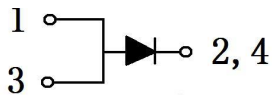
/ Features

High Forward Surge Capability, Ultra Low Forward Voltage Drop, Excellent High Temperature Stability.

/ Applications

For use in low voltage,high frequency inverters, free wheeling, and polarity protection applications.

/ Equivalent Circuit



/ Pinning



PIN1 Anode

PIN 2,4 Cathode

PIN 3 Anode

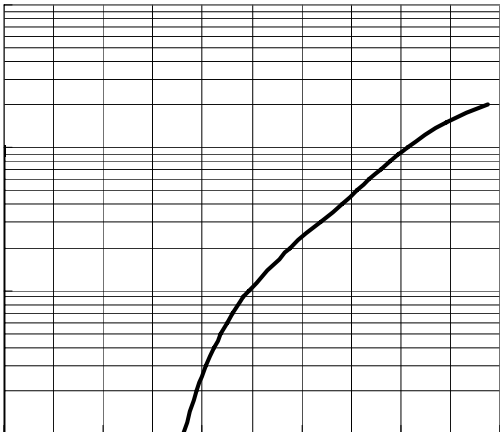
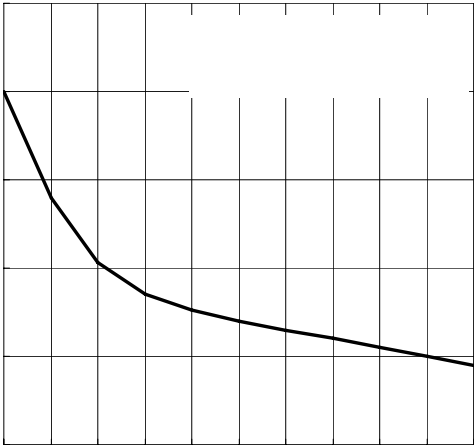
/ h_{FE} Classifications & Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	150	V
RMS Reverse Voltage	V_{RMS}	105	V
Average forward rectified current	$I_{F(AV)}$	1×10	A
Non Repetitive Peak Surge Current	I_{FSM}	200	A
Thermal Resistance Junction to Case	R_{JC}	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R=1mA(T_a=25^\circ C)$	150			V
Forward Voltage	V_F	$I_F=2A(T_a=25^\circ C)$		0.58		V
		$I_F=10A(T_a=25^\circ C)$		0.81	0.85	V
		$I_F=2A(T_a=125^\circ C)$		0.47		V
		$I_F=10A(T_a=125^\circ C)$		0.69	75	V
Instantaneous Reverse Current	I_R Note 1	$V_R=150V(T_a=25^\circ C)$		5	50	A
		$V_R=150V(T_a=125^\circ C)$			20	mA

/ Electrical Characteristic Curve



Technical drawings of a mechanical component, showing front and side views with dimensions.

Front View (Left):

- Overall width: D
- Top flange thickness: B
- Top flange outer diameter: ϕ
- Top flange inner diameter: ϕ_1
- Top flange height: E
- Central hole diameter: $L3$
- Bottom flange thickness: 2
- Bottom flange outer diameter: $b1$
- Bottom flange inner diameter: b
- Bottom flange height: $e1$
- Bottom flange width: $e2$

Side View (Right):

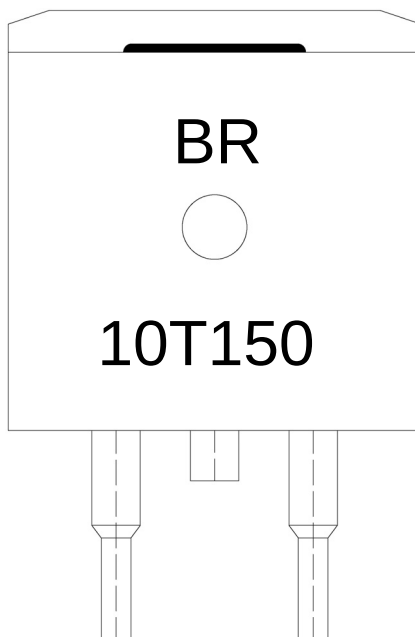
- Overall height: $L1$
- Top flange width: A
- Top flange thickness: C
- Bottom flange thickness: 2
- Bottom flange width: $b2$

單位: mm

			Dimensions In Millimeters			Dimensions In Millimeters		
			Symbol		Symbol		Symbol	
			Min	Max	Min	Max	Min	Max
			A	4.30	4.70	E	9.00	9.40
			B	1.00	1.40	e1	2.34	2.74
			b	0.70	0.90	e2	4.88	5.28
			C	8.10	8.50	L2	2.24	2.64
			C	1.20	1.40	L3	1.20	1.60
			D	9.80	10.20			

ТД-263

/ Marking Instructions



BR

10T150

Note:

BR:

Company Code

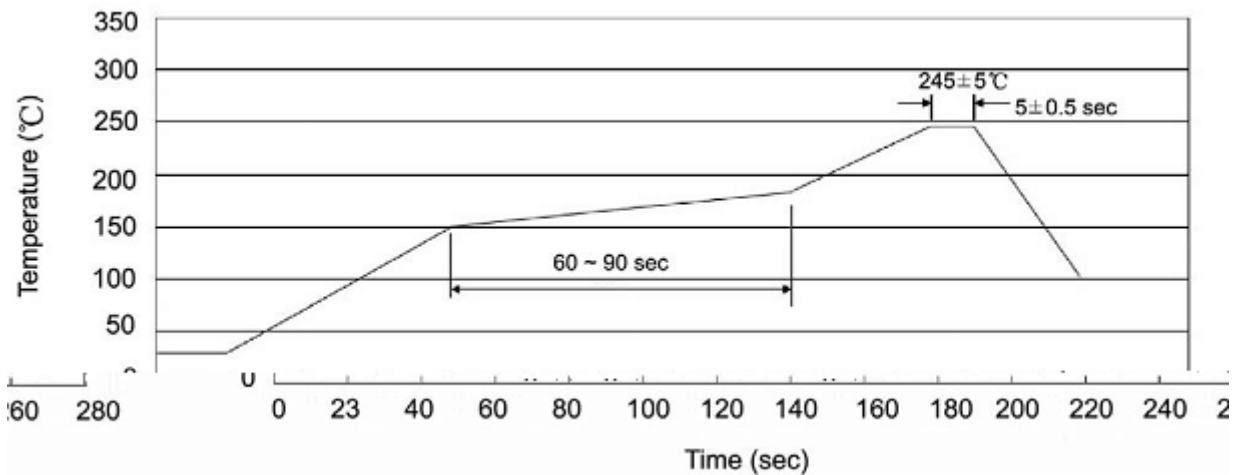
10T150

Product Type.

****:

Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices